

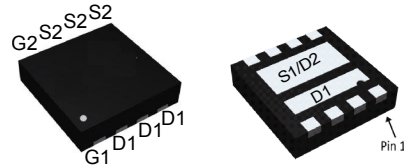
### Features

- **Channel 1**  
30V/18A,  
 $R_{DS(ON)} = 7\text{ m}\Omega$  (typ.) @  $V_{GS} = 10\text{V}$   
 $R_{DS(ON)} = 10\text{m}\Omega$  (typ.) @  $V_{GS} = 4.5\text{V}$
- **Channel 2**  
30V/18A,  
 $R_{DS(ON)} = 7\text{ m}\Omega$  (typ.) @  $V_{GS} = 10\text{V}$   
 $R_{DS(ON)} = 10\text{m}\Omega$  (typ.) @  $V_{GS} = 4.5\text{V}$
- 100% UIS Tested
- Reliable and Rugged
- Lead Free Available (RoHS Compliant)

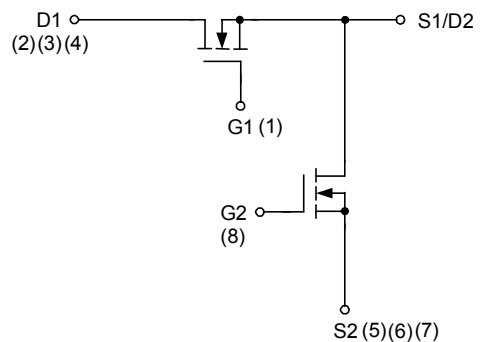
### Applications

- Power Management in Desktop Computer or DC/DC Converters.

### Pin Description



TDFN3x3-8\_EP2



N-Channel MOSFET

**Absolute Maximum Ratings** ( $T_A = 25^\circ\text{C}$  unless otherwise noted)

Symbol	Parameter		Channel 1	Channel 2	Unit
<b>Common Ratings</b>					
$V_{DSS}$	Drain-Source Voltage		30	30	V
$V_{GSS}$	Gate-Source Voltage		$\pm 20$	$\pm 20$	
$T_J$	Maximum Junction Temperature		150		$^\circ\text{C}$
$T_{STG}$	Storage Temperature Range		-55 to 150		
$I_S$	Diode Continuous Forward Current	$T_C=25^\circ\text{C}$	18	18	A
$I_D^a$	Continuous Drain Current	$T_C=25^\circ\text{C}$	18	18	A
$I_{DM}^b$	Pulse Drain Current Tested	$T_C=25^\circ\text{C}$	54	54	A
$P_D$	Maximum Power Dissipation	$T_C=25^\circ\text{C}$	20	20	W
$R_{\theta JC}$	Thermal Resistance-Junction to Case	Steady State	6	6	$^\circ\text{C}/\text{W}$
$I_D^c$	Continuous Drain Current	$T_A=25^\circ\text{C}$	8.4	9.1	A
		$T_A=70^\circ\text{C}$	6.7	7.3	
$I_{DM}$	Pulse Drain Current Tested	$T_A=25^\circ\text{C}$	33.5	36	A
$P_D^c$	Maximum Power Dissipation	$T_A=25^\circ\text{C}$	1.14	1.3	W
		$T_A=70^\circ\text{C}$	0.7	0.8	
$R_{\theta JA}$	Thermal Resistance-Junction to Ambient	$t \leq 10\text{s}$	66	60	$^\circ\text{C}/\text{W}$
		Steady State <sup>c</sup>	110	100	
$I_{AS}^d$	Avalanche Current, Single pulse	$L=0.1\text{mH}$	15	15	A
		$L=0.5\text{mH}$	9	9	
$E_{AS}^d$	Avalanche Energy, Single pulse	$L=0.1\text{mH}$	11.25	11.25	mJ
		$L=0.5\text{mH}$	20.3	20.3	

Note a,\* : Max. continuous current is limited by bonding wire.

Note b : Pulse width is limited by max. junction temperature.

Note c :  $R_{\theta JA}$  steady state  $t=999\text{s}$ .

Note d : UIS tested and pulse width limited by maximum junction temperature  $150^\circ\text{C}$  (initial temperature  $T_J=25^\circ\text{C}$ ).

**Electrical Characteristics** ( $T_A = 25^\circ\text{C}$  unless otherwise noted)

Symbol	Parameter	Test Conditions	Channel 1			Unit
			Min.	Typ.	Max.	
<b>Static Characteristics</b>						
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_{DS}=250\mu A$	30	-	-	V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=24V, V_{GS}=0V$	-	-	1	$\mu A$
		$T_J=85^\circ C$	-	-	30	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_{DS}=250\mu A$	1.4	1.8	2.5	V
$I_{GSS}$	Gate Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	$\pm 100$	nA
$R_{DS(ON)}^e$	Drain-Source On-state Resistance	$V_{GS}=10V, I_{DS}=10A$	-	7	10	m $\Omega$
		$V_{GS}=4.5V, I_{DS}=8A$	-	10	15	
<b>Diode Characteristics</b>						
$V_{SD}^e$	Diode Forward Voltage	$I_{SD}=5A, V_{GS}=0V$	-	0.8	1.1	V
$t_{rr}$	Reverse Recovery Time	$I_{DS}=10A, di_{SD}/dt=100A/\mu s$	-	20.5	-	ns
$Q_{rr}$	Reverse Recovery Charge		-	7.2	-	nC
<b>Dynamic Characteristics<sup>f</sup></b>						
$R_G$	Gate Resistance	$V_{GS}=0V, V_{DS}=0V, F=1MHz$	-	1.35	2.5	$\Omega$
$C_{iss}$	Input Capacitance	$V_{GS}=0V,$ $V_{DS}=15V,$ Frequency=1.0MHz	-	455	600	pF
$C_{oss}$	Output Capacitance		-	318	-	
$C_{rss}$	Reverse Transfer Capacitance		-	22	-	
$t_{d(ON)}$	Turn-on Delay Time		$V_{DD}=15V, R_L=15\Omega,$ $I_{DS}=1A, V_{GEN}=10V,$ $R_G=6\Omega$	-	8.5	16
$t_r$	Turn-on Rise Time	-		10	18	
$t_{d(OFF)}$	Turn-off Delay Time	-		14	26	
$t_f$	Turn-off Fall Time	-		10.6	19	
<b>Gate Charge Characteristics<sup>f</sup></b>						
$Q_g$	Total Gate Charge	$V_{DS}=15V, V_{GS}=10V,$ $I_{DS}=10A$	-	8	12	nC
$Q_{gs}$	Gate-Source Charge		-	1.6	-	
$Q_{gd}$	Gate-Drain Charge		-	1.2	-	

 Note e : Pulse test ; pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .

Note f : Guaranteed by design, not subject to production testing.

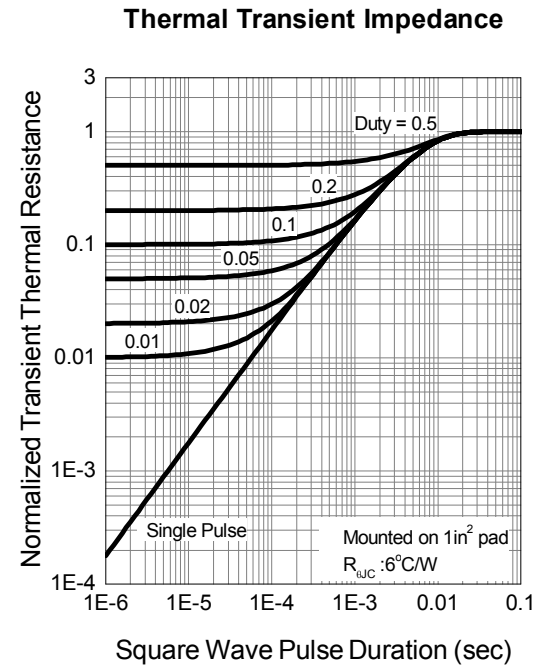
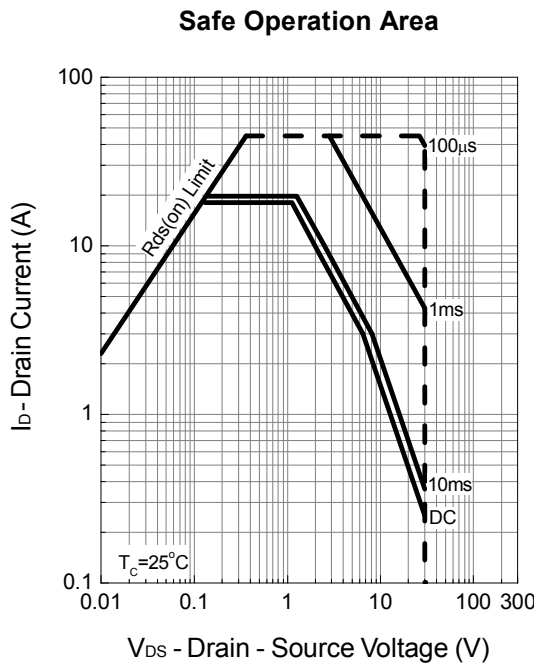
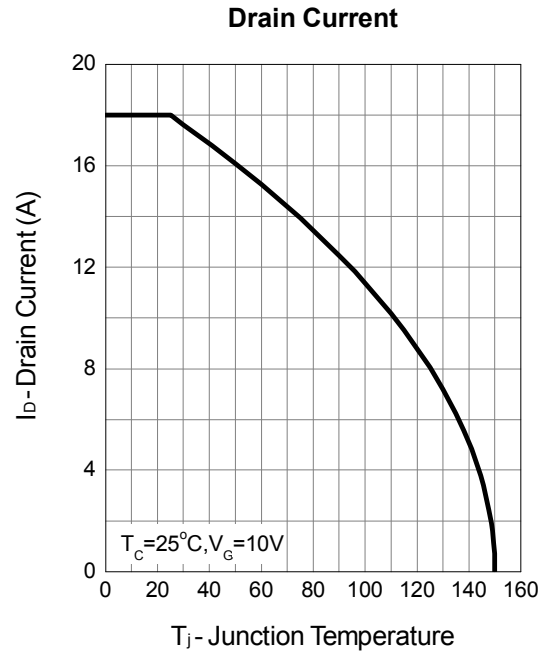
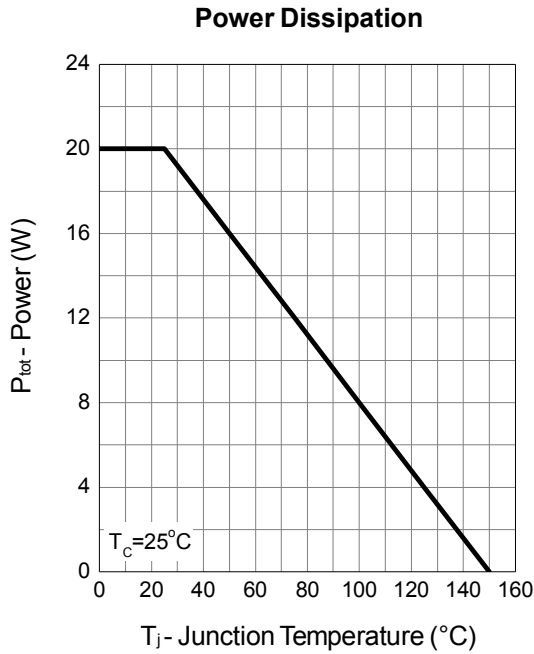
**Electrical Characteristics** ( $T_A = 25^\circ\text{C}$  unless otherwise noted)

Symbol	Parameter	Test Conditions	Channel 2			Unit
			Min.	Typ.	Max.	
<b>Static Characteristics</b>						
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_{DS}=250\mu A$	30	-	-	V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=24V, V_{GS}=0V$	-	-	1	$\mu A$
		$T_J=85^\circ C$	-	-	30	mA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_{DS}=-250\mu A$	1.3	1.8	2.5	V
$I_{GSS}$	Gate Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	$\pm 100$	nA
$R_{DS(ON)}^e$	Drain-Source On-state Resistance	$V_{GS}=10V, I_{DS}=10A$	-	7	10	m $\Omega$
		$V_{GS}=4.5V, I_{DS}=8A$	-	10	15	
<b>Diode Characteristics</b>						
$V_{SD}^e$	Diode Forward Voltage	$I_{SD}=5A, V_{GS}=0V$	-	0.8	1.3	V
$t_{rr}$	Reverse Recovery Time	$I_{DS}=10A, di_{SD}/dt=100A/\mu s$	-	20.5	-	ns
$Q_{rr}$	Reverse Recovery Charge		-	7.2	-	nC
<b>Dynamic Characteristics<sup>f</sup></b>						
$R_G$	Gate Resistance	$V_{GS}=0V, V_{DS}=0V, F=1MHz$	-	1.35	2.5	$\Omega$
$C_{iss}$	Input Capacitance	$V_{GS}=0V, V_{DS}=15V, Frequency=1.0MHz$	-	455	600	pF
$C_{oss}$	Output Capacitance		-	318	-	
$C_{rss}$	Reverse Transfer Capacitance		-	22	-	
$t_{d(ON)}$	Turn-on Delay Time		$V_{DD}=15V, R_L=15\Omega, I_{DS}=1A, V_{GEN}=10V, R_G=6\Omega$	-	8.5	16
$t_r$	Turn-on Rise Time	-		10	18	
$t_{d(OFF)}$	Turn-off Delay Time	-		14	26	
$t_f$	Turn-off Fall Time	-		10.6	19	
<b>Gate Charge Characteristics<sup>f</sup></b>						
$Q_g$	Total Gate Charge	$V_{DS}=15V, V_{GS}=10V, I_{DS}=10A$	-	8	12	nC
$Q_{gs}$	Gate-Source Charge		-	1.6	-	
$Q_{gd}$	Gate-Drain Charge		-	1.2	-	

 Note e : Pulse test; pulse width $\leq 300\mu s$ , duty cycle $\leq 2\%$ .

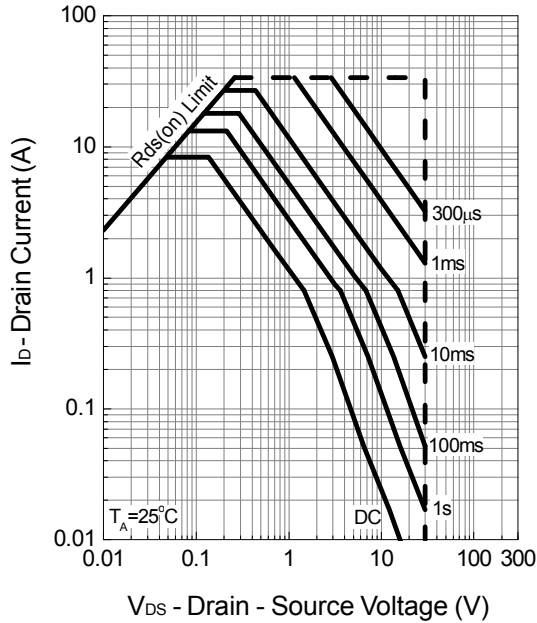
Note f : Guaranteed by design, not subject to production testing.

### Channel 1 Typical Operating Characteristics

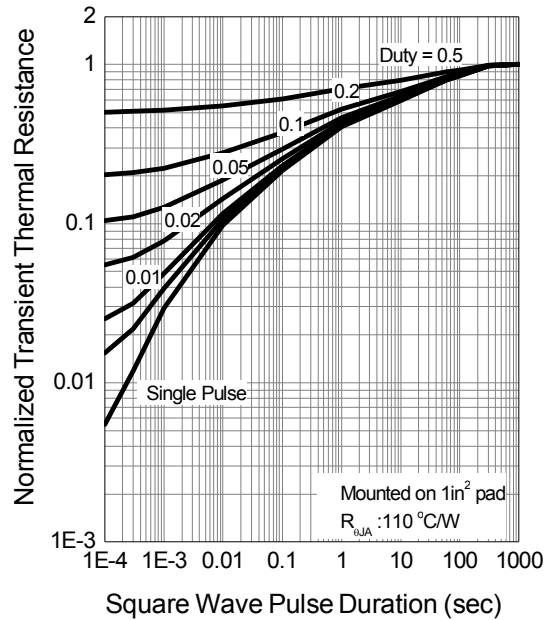


### Channel 1 Typical Operating Characteristics (Cont.)

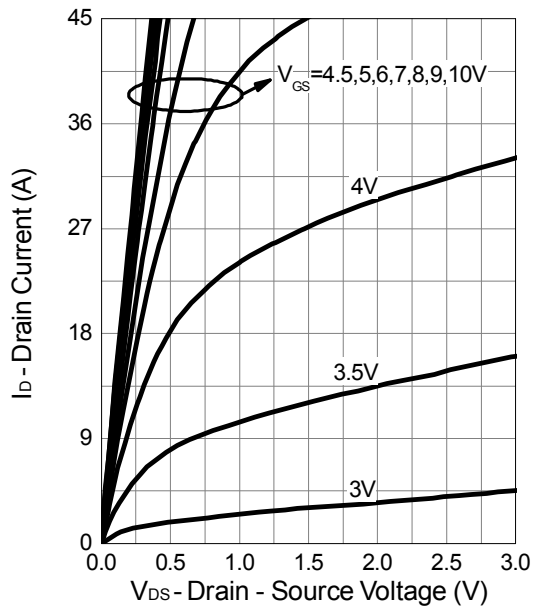
Safe Operation Area



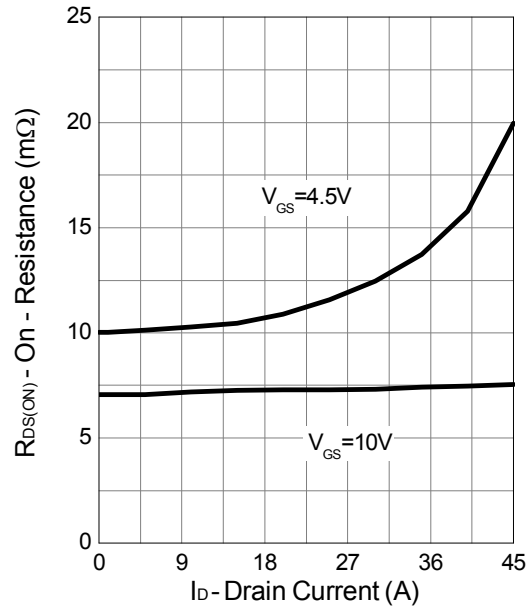
Thermal Transient Impedance



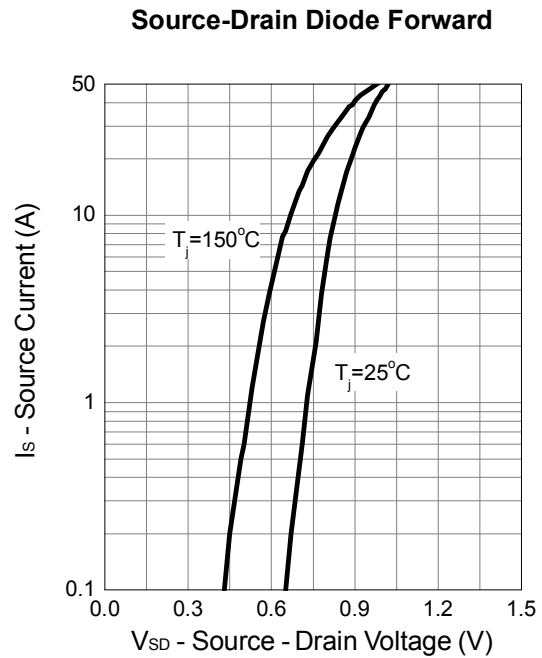
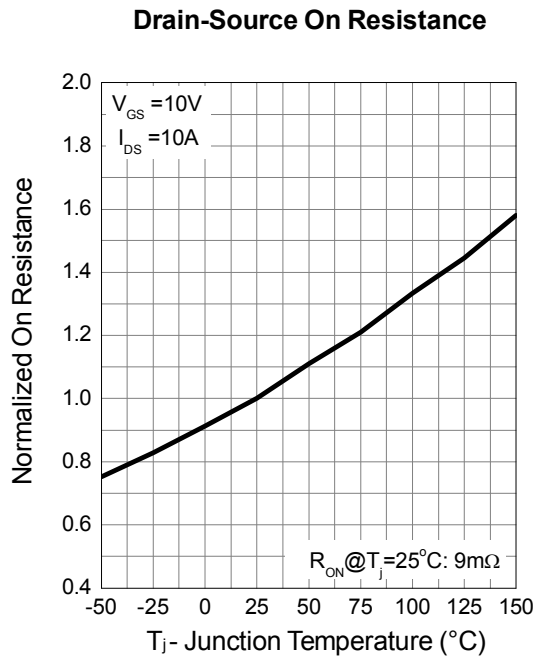
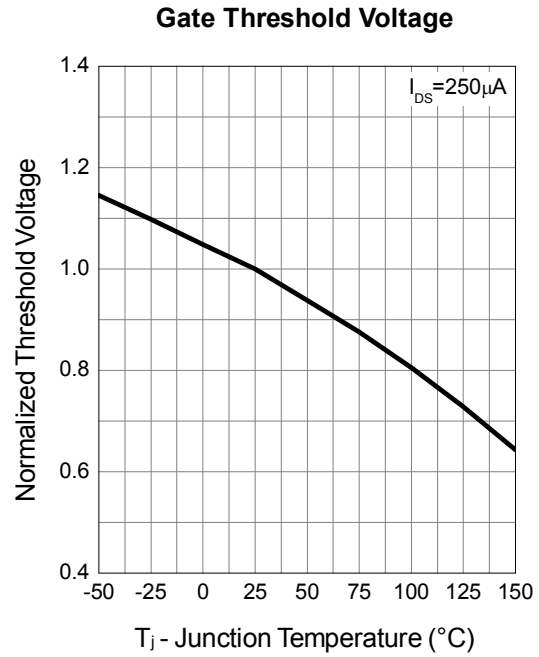
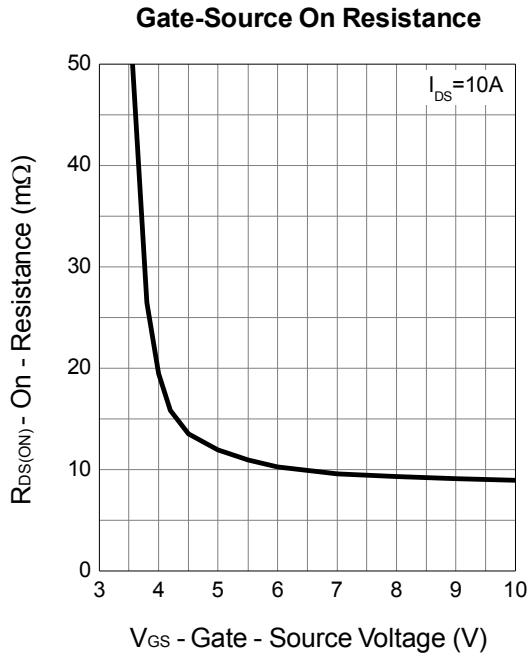
Output Characteristics



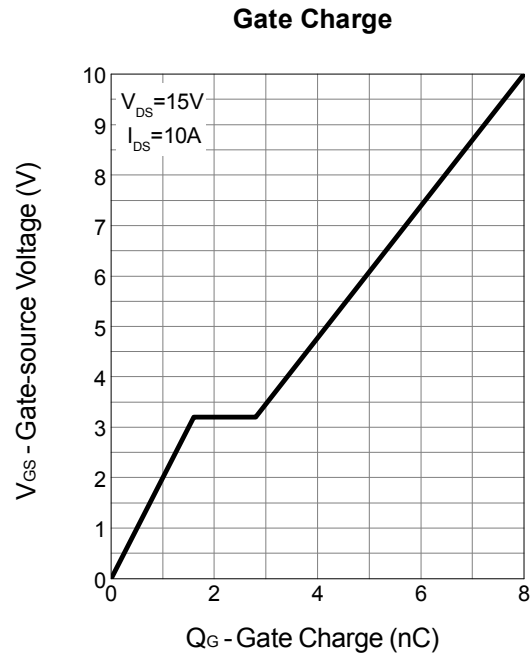
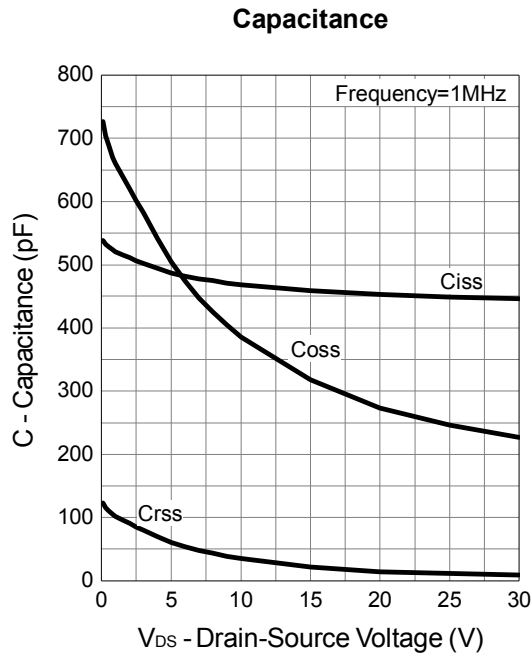
Drain-Source On Resistance



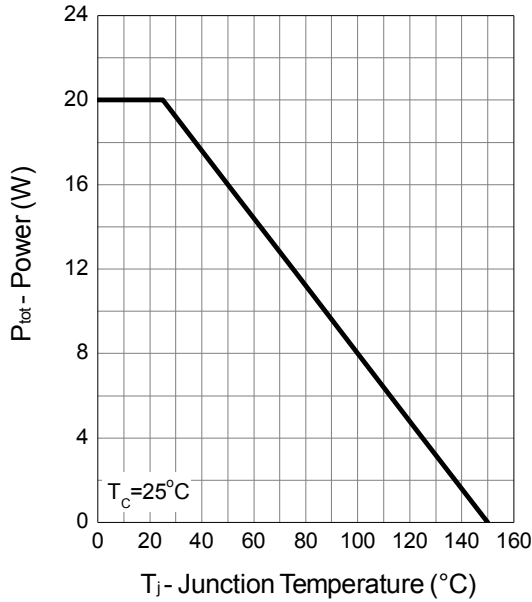
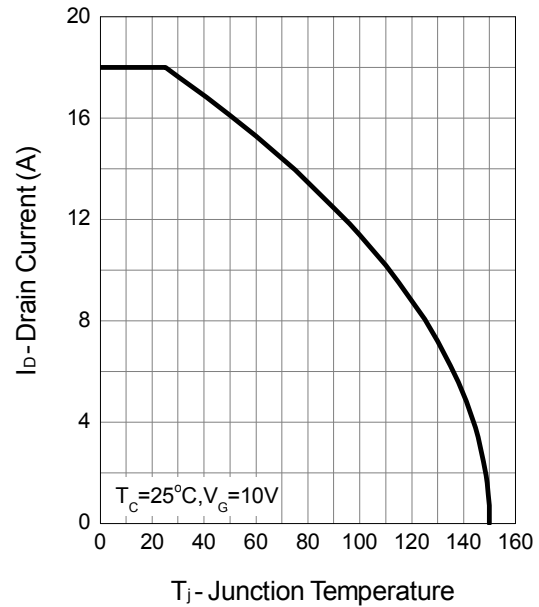
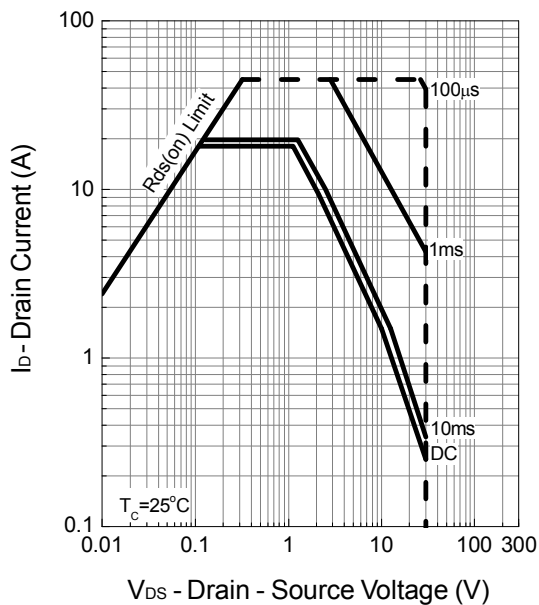
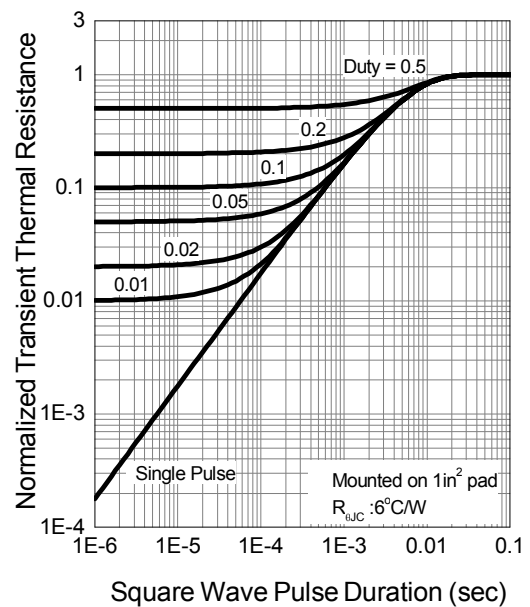
## Channel 1 Typical Operating Characteristics (Cont.)



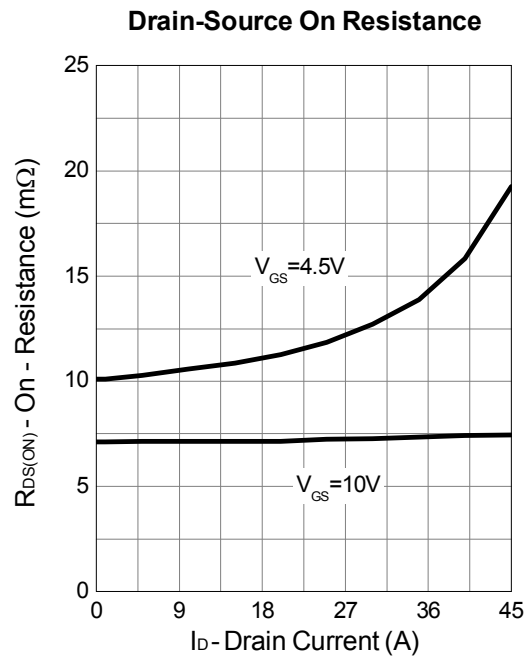
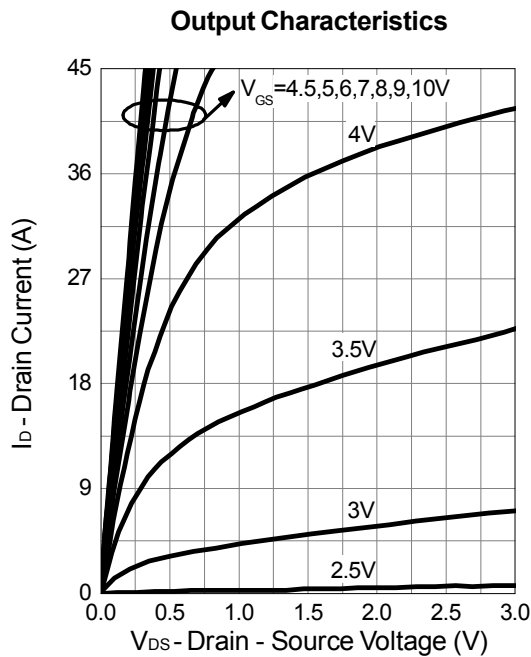
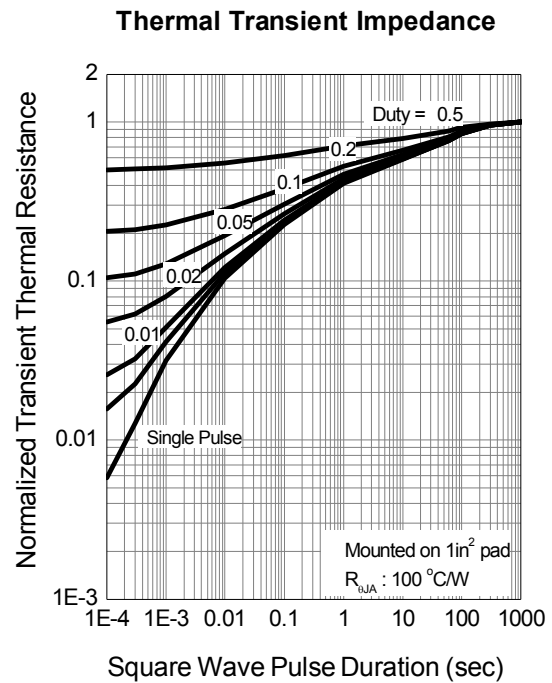
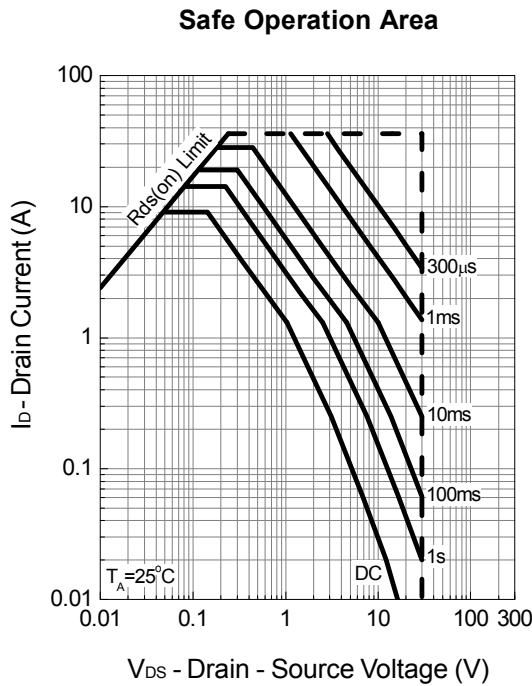
### Channel 1 Typical Operating Characteristics (Cont.)



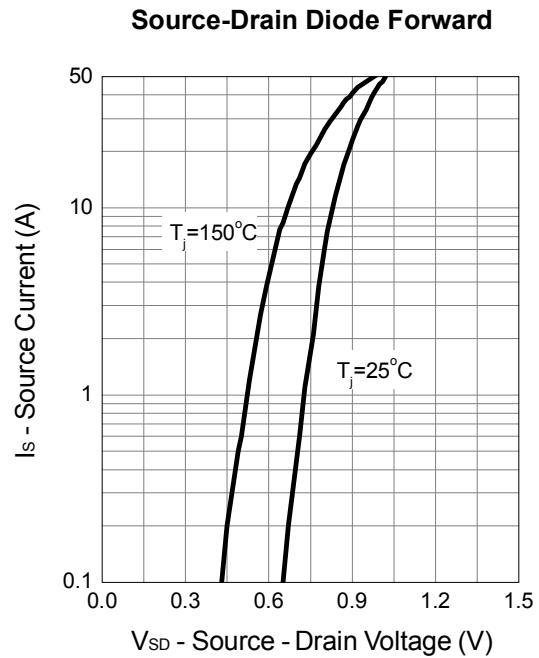
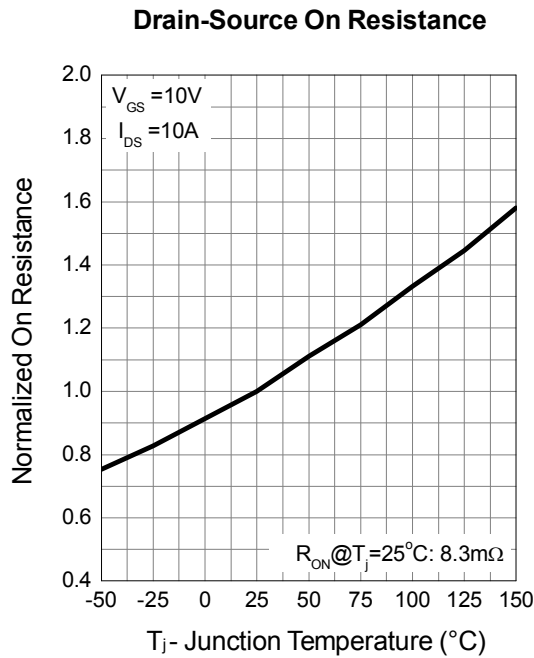
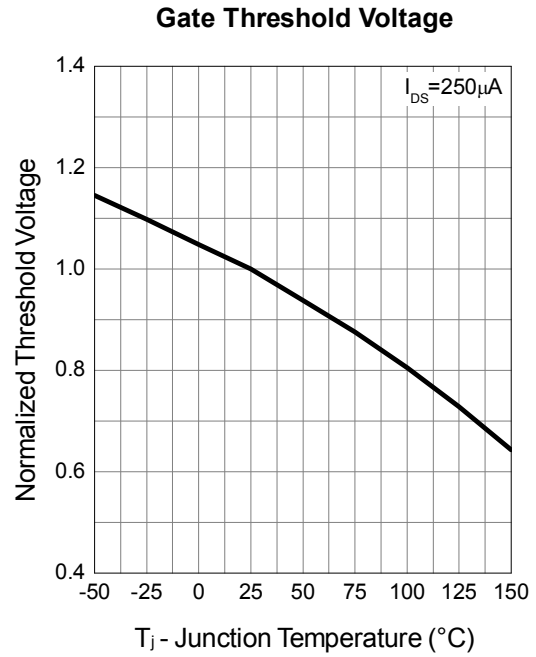
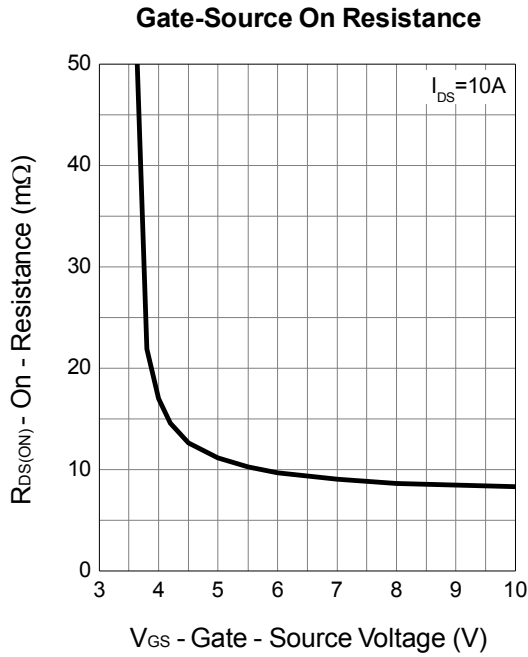
## Channel 2 Typical Operating Characteristics

**Power Dissipation**

**Drain Current**

**Safe Operation Area**

**Thermal Transient Impedance**


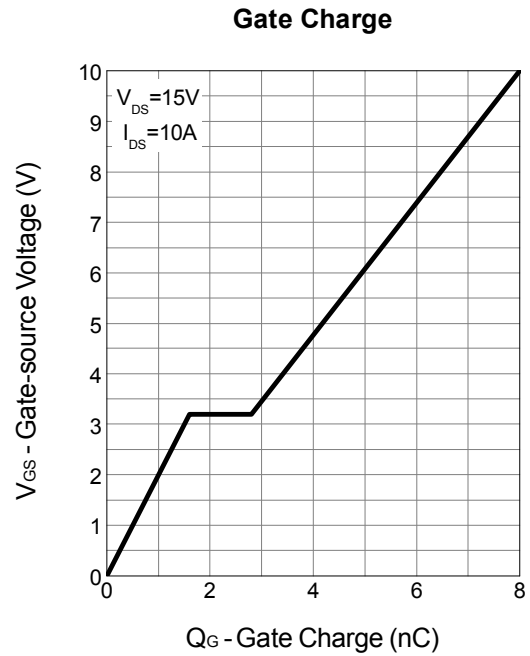
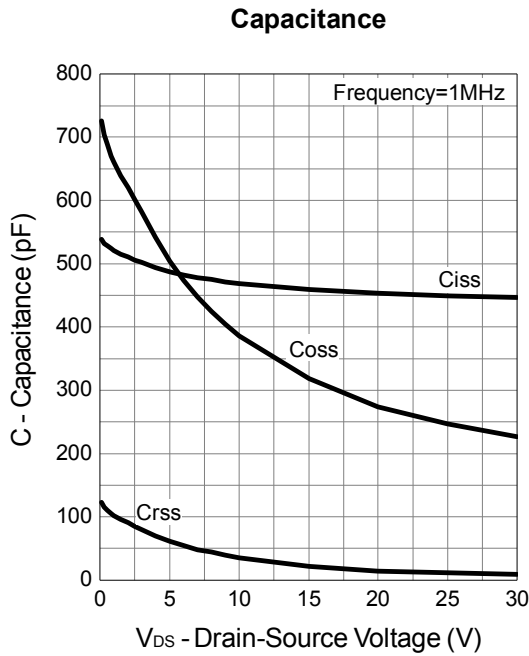
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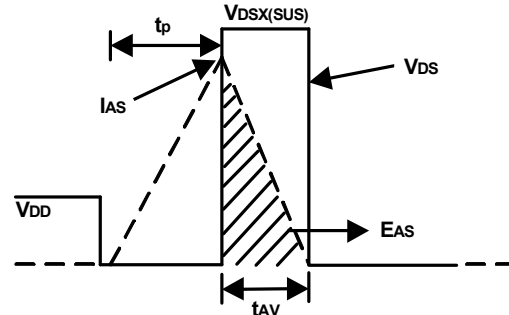
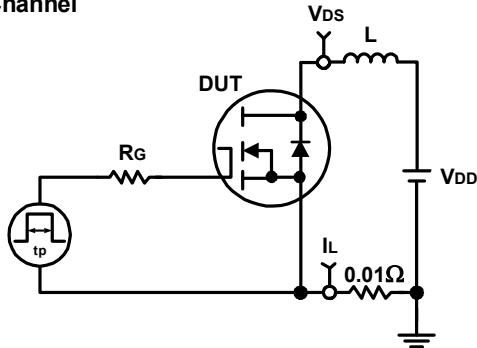
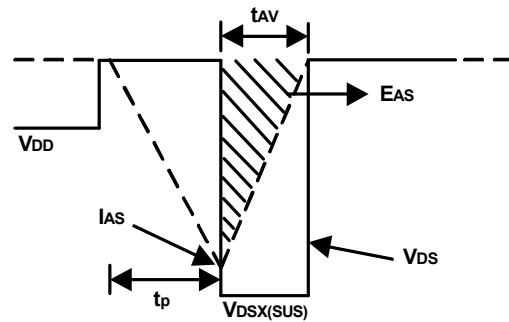
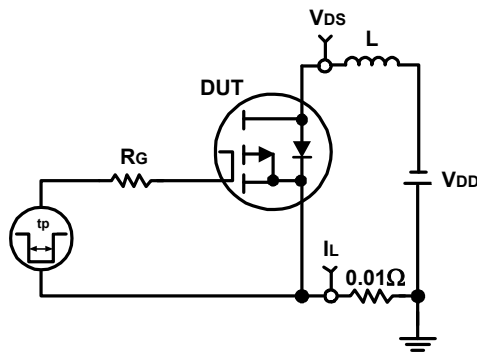
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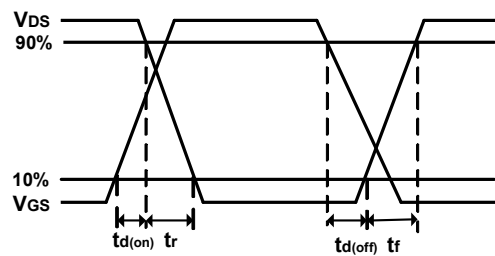
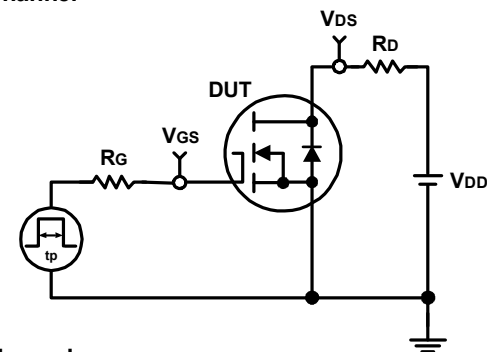
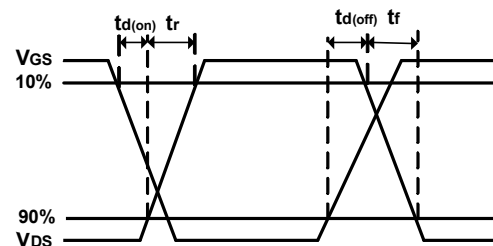
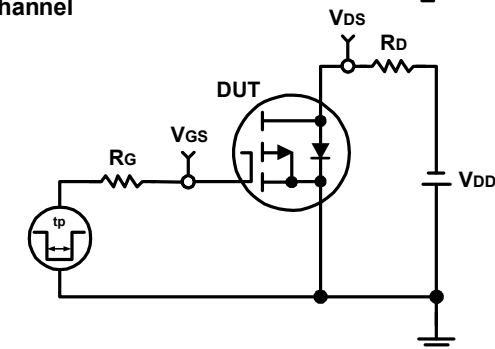
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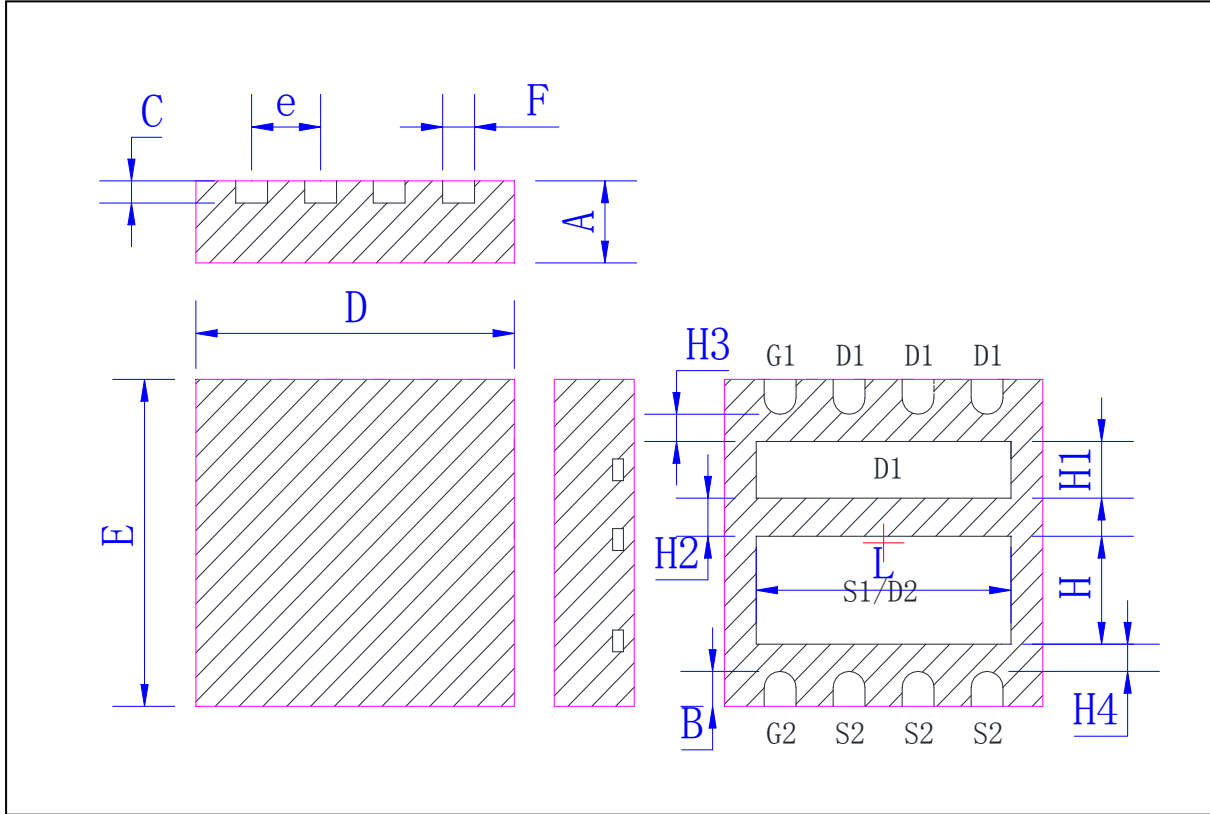


## Avalanche Test Circuit and Waveforms

**N Channel**

**P Channel**


## Switching Time Test Circuit and Waveforms

**N Channel**

**P Channel**


**TDFN3\*3-8\_EP2 OUTLINE**


Symbol	Min	Typ	Max
A	0.70	0.75	0.80
B	0.27	0.32	0.37
C	0.153	0.203	0.253
D	2.90	3.00	3.10
E	2.90	3.00	3.10
e	0.60	0.65	0.70
F	0.25	0.30	0.35
H	0.89	0.99	1.09
H1	0.42	0.52	0.62
H2	0.25	0.35	0.45
H3	0.15	0.25	0.35
H4	0.15	0.25	0.35
L	2.30	2.40	2.50